

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
10 February 2005 (10.02.2005)

PCT

(10) International Publication Number
WO 2005/013367 A1

(51) International Patent Classification⁷: **H01L 27/02**

(21) International Application Number:
PCT/KR2004/001759

(22) International Filing Date: 15 July 2004 (15.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10-2003-0052561 30 July 2003 (30.07.2003) KR
10-2003-0052562 30 July 2003 (30.07.2003) KR

(71) Applicant (for all designated States except US): **IN-NOCHIPS TECHNOLOGY CO., LTD.** [KR/KR]; 2F, 418-21, Daeya-dong, Siheung 429-010 (KR).

(71) Applicants and

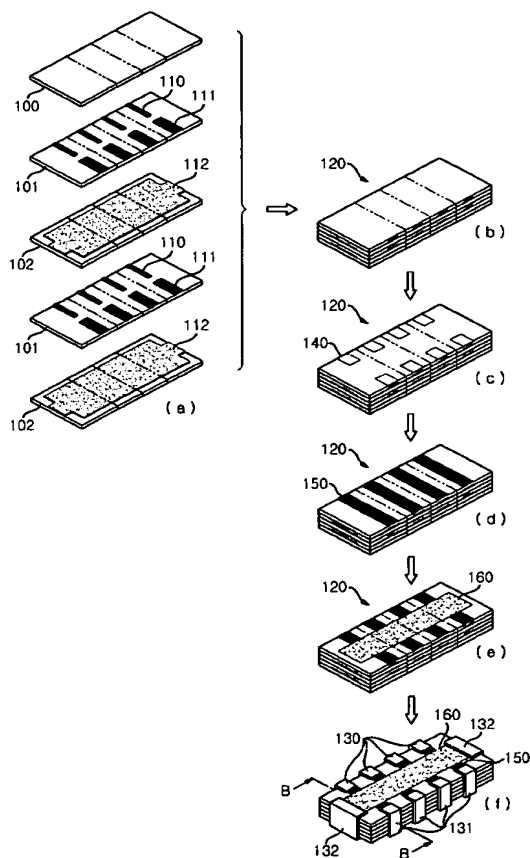
(72) Inventors: **PARK, In-Kil** [KR/KR]; Injung Apt. 105-804, Dangsudong, Kwonsun-gu, Suwon 441-180 (KR). **HWANG, Soon-Ha** [KR/KR]; 196-7, Woomyeon-dong, Seocho-gu, Seoul 137-901 (KR). **KIM, Duk-Hee** [KR/KR]; Bak-Du Hanyang Apt. 982-502, Sanbon-dong, Gunpo 435-040 (KR).

(74) Agent: **NAM, Seung-Hee**; 2F, Myung-Jin Bldg., 746-9 Yeoksam-dong, Gangnam-Gu, Seoul 135-080 (KR).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

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(54) Title: **COMPLEX LAMINATED CHIP ELEMENT**



(57) Abstract: The present invention relates to a laminated chip element which can be manufactured to have desired electric properties by combining various elements in accordance with the desired objectives. More particularly, the present invention relates to a laminated chip element which has superior high frequency properties and can be manufactured to control capacitance and/or inductance of the laminated chip element to a desired value. There is provided a laminated chip element, comprising at least one first sheet on which first and second conductive patterns are formed, the first and second conductive patterns being spaced apart from each other in a direction of both ends of the first sheet; and at least one second sheet on which a third conductive pattern is formed, the third conductive pattern being formed in a transverse direction of both the ends of the first sheet; wherein one ends of the first and second conductive patterns are connected to first and second external terminals, respectively, at least one end of the third conductive pattern is connected to a third external terminal, and the first and second sheets are laminated. There is also provided a laminated chip element, comprising: at least one first sheet on which a first conductive pattern is formed, the first conductive pattern consisting of first to third portions, the first and second portions being spaced apart from each other in a direction of both ends of the first sheet, the second portion connecting the first and second portions to each other to have a predetermined inductance; and at least one second sheet on which a second conductive pattern is formed in a transverse direction of both the ends of the first sheet; wherein the first and second portions are connected to first and second external terminals, respectively, at least one ends of the second conductive pattern is connected to a third external terminal, and the first and second sheets are laminated.



(84) **Designated States** (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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